



RESPONSE UNDER 37CFR1.116
EXPEDITED PROCEDURE
EXAMINING GROUP # 1731

AF
IFW

In The United States Patent And Trademark Office

Application Number: 10/082,867
Application Filed: 02/18/2002
Applicants: Romain L. Billiet et al.
Title: Ultrasmall Semiconductor Bonding Tools and Method of
Fabrication Thereof
Examiner/GAU: Carlos N. Lopez/1731

Penang, Malaysia, Monday, March 6, 2006

AMENDMENT UNDER 37 CFR 1.116

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Commissioner for Patents
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Sir:

In response to the Final Office Action mailed on December 7, 2005, applicants request that above application be amended as follows to place it in condition for allowance: